

EchoPilot Carrier Rev 1b Fabrication Notes

Stackup:

10 Layer, Layer order F.Cu, Gnd1.Cu, In1.Cu, In2.Cu, Pwr1.Cu, Gnd2.Cu, In3.Cu, In4.Cu, Pwr2.Cu, B.Cu

Target thickness: 62.5 mil

Spacing: 4/4

Finish: ENIG, 1.0 oz copper

Stackup: 10-layer PCB , Board house can define stackup to achieve impedance structures below.

Solder Mask: Blue

Silkscreen: White

90 ohm impedance structure

Traces can be identified by unique widths:

F.Cu: 6.2 mils

In1.Cu: 6.2 mils

In2.Cu: 6.2 mils

In3.Cu: 6.2 mils

In4.Cu: 6.2 mils

B.Cu: 6.2 mils

100 ohm impedance structure

Traces can be identified by unique widths:

F.Cu: 5.7 and 5.01 mils

In1.Cu: 5.7 and 5.01 mils

In2.Cu: 5.01mils

In3.Cu: 5.01 and 5.7 mils

In4.Cu: 5.01 mils

B.Cu: 5.7 and 5.01 mils

120 ohm impedance structure

Traces can be identified by unique widths:

F.Cu: 4.02 mils

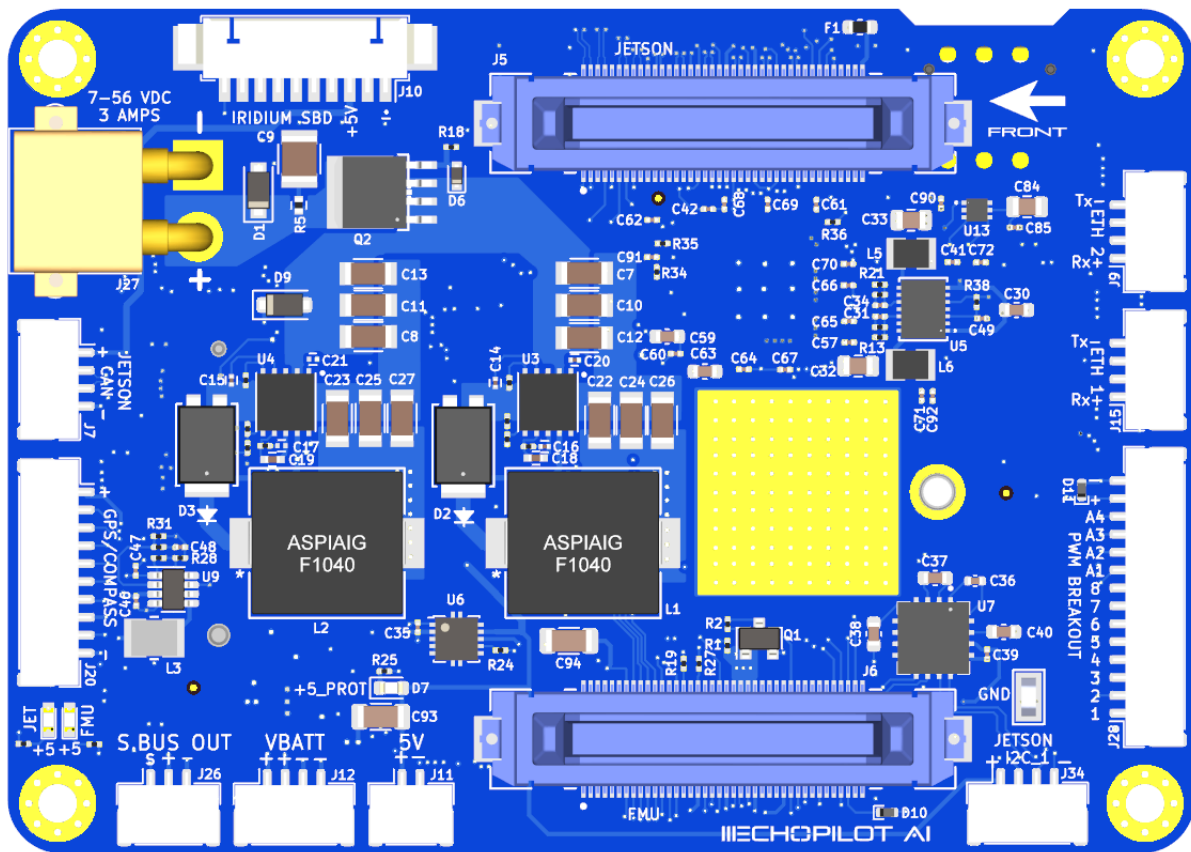
In1.Cu: 4.02 mils

In2.Cu: 4.02 mils

In3.Cu: 4.02 mils

In4.Cu: 4.02 mils

B.Cu: 4.02 mils



Note the through-hole pins shown must be soldered!

